The 2nd International Symposium on

Advanced Power Packaging

November 5～7, 2025

Fukuoka International Congress Center

Fukuoka, Japan

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The 2025 International Symposium on Advanced Power Packaging (ISAPP2025) will be held from November 5th ~7th, at Fukuoka International Congress Center, Fukuoka, Japan. This international symposium aims to gather and evaluate all the aspects of science, technology, and business in the fields of the next generation packaging technology and passive components of power electronics especially for wide band gap semiconductors (WBGs) and to review their reliability issues on power electronics applications including electric mobilities such as cars, trains, airplanes, industrial/humanoid robots, IoT, and renewable energies/energy grids. This symposium will bring together key persons from all over the world and from every sector of academy and industry in the field of next generation power electronics.

Main Topics

1. Packaging Materials

Die bonding, wiring, connecting, substrates(ceramic/organic), thermal interface material (TIM), encapsulant for junction temperature beyond 200 ° C

2. Process Technologies and Machines

Electrode bonding method to power devices, in-package wiring method, mounting of active and passive elements, external electrode extraction structure, encapsulation method and equipment to achieve these, package concepts for fast-switching devices

3. Integration and Packaging

Packaging for advanced power electronics; system integration, 3D packaging, integration technologies, interconnection technologies, cooling system

4. Reliability, Test and Simulation

Thermal measurement, thermal management, electric measurements, reliability test (power cycling, thermal shock, etc.), simulation and modeling

Important Dates

Abstract submission deadline	~~June 15, 2025~~ ~~July 30~~ ~~August 22~~ **September 20**
Notification of acceptance	~~July 31, 2025~~ ~~August 30~~ **September 25**
Final paper submission	~~August 31, 2025~~ **October 20**

web site https://isapp.jp/